IEEE ESTC EPS

CALL FOR PAPERS

September 9–11, 2026 in Helsinki, Finland

IEEE ESTC 2026

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The IEEE Electronics System-Integration Technology Conference (IEEE ESTC) is the premier international event in the field of electronics packaging and system integration. The conference is held biennially in Europe. It is sponsored by IEEE-EPS and co-sponsored by IMAPS Europe. The 11th IEEE ESTC will be taking place in Helsinki, the capital of Finland.

The IEEE ESTC 2026 seeks original, noncommercial papers describing research and innovations in all areas of electronics packaging and system integration. Authors are invited to submit a **600-word-abstract** describing recent work. Abstracts must detail the objectives of the work presented and demonstrate new results.

CONFERENCE TOPICS:

- Advanced Packaging
- Materials for Interconnects and Packaging
- Optoelectronic Systems Packaging
- Assembly and Manufacturing Technologies
- Design Tools and Modeling
- Power Electronics System Packaging
- Advanced Technologies for Emerging Systems
- Reliability of Electronic Devices and Systems
- Flexible, Printed and Hybrid Electronics
- RF, mm-wave and THz Systems Packaging

The technical program will include oral talks, poster presentations, an exhibition, special sessions and invited keynote talks given by renowned speakers.

Proceedings

Accepted contributions will be published in the conference proceedings, and archived in IEEE Xplore (provided they comply with specifications). IEEE ESTC papers can be searched through IEEE, Google Scholar and other search engines.

Sponsors and exhibitors welcome!

The IEEE ESTC 2026 offers attractive packages for sponsors and exhibitors! Please contact the organizing committee for further details: exhibition@estc-conference.net.

IEEE ESTC Student Travel Award

The student travel grant program for IEEE ESTC awards up to 20 grants. The competition is open to all full-time graduate students enrolled at an accredited institution in a program of study within the scope of IEEE ESTC. The student must be listed as the primary author on the abstract.

Please check the conference website for details on hotel bookings and travel arrangements.

Important dates:

Conference: September 9-11, 2026
Abstract submission opens: December 1, 2025
Abstract submission deadline: March 1, 2026
Notification of acceptance: April 5, 2026
Paper submission deadline: May 31, 2026

ABSTRACT SUBMISSION

Submit your abstract of 600 words (max.) and up to 2 (optional) figures at

https://www.conftool.org/estc2026

VENUE

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CONTACT

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